

# ES3A THRU ES3J

**Surface Mount Superfast Recovery Rectifier**  
**Reverse Voltage – 50 to 600 V**  
**Forward Current –3 A**

## FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Superfast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

## MECHANICAL DATA

- Case : SMB
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight : 0.1g / 0.003oz

## PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Top View  
 Marking Code: ES3A~ES3J  
 Simplified outline SMB and symbol

## Absolute Maximum Ratings and Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

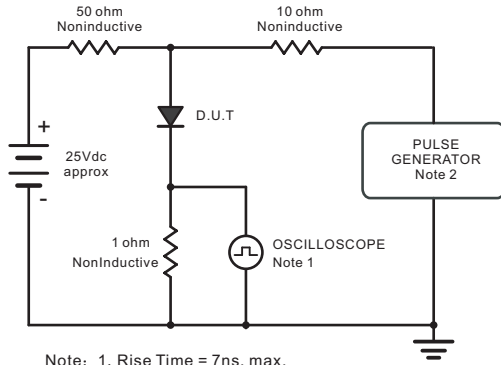
Parameter	Symbols	ES3A	ES3B	ES3C	ES3D	ES3E	ES3G	ES3J	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	150	200	300	400	600	V
Maximum RMS voltage	$V_{RMS}$	35	70	105	140	210	280	420	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	150	200	300	400	600	V
Maximum Average Forward Rectified Current at $T_c = 100\text{ }^\circ\text{C}$	$I_{F(AV)}$	3							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	$I_{FSM}$	90							A
Maximum Forward Voltage at 3 A	$V_F$	1				1.25		1.68	V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a = 25\text{ }^\circ\text{C}$ $T_a = 125\text{ }^\circ\text{C}$	$I_R$	5 100							$\mu\text{A}$
Typical Junction Capacitance at $V_R=4\text{V}$ , $f=1\text{MHz}$	$C_j$	45							pF
Maximum Reverse Recovery Time <sup>(1)</sup>	$t_{rr}$	35							ns
Typical Thermal Resistance <sup>(2)</sup>	$R_{\theta JA}$ $R_{\theta JC}$	50 16							$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150							$^\circ\text{C}$

( 1 ) Measured with  $I_F = 0.5\text{ A}$ ,  $I_R = 1\text{ A}$ ,  $I_{rr} = 0.25\text{ A}$ .

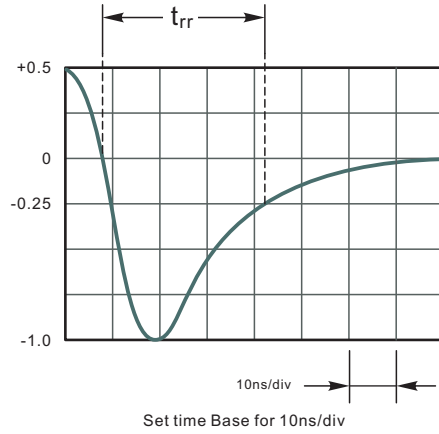
( 2 ) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

# ES3A THRU ES3J

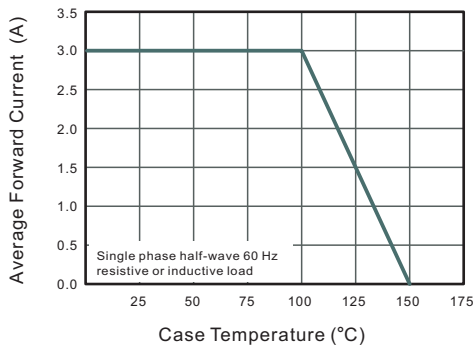
**Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram**



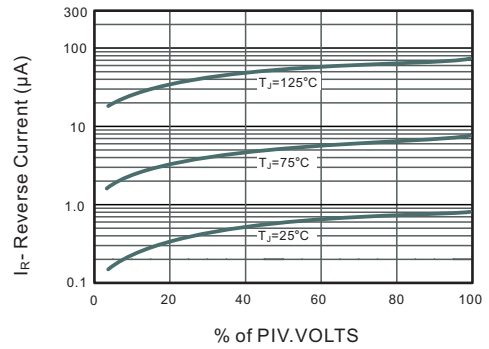
Note: 1. Rise Time = 7ns, max.  
 Input Impedance = 1megohm, 22pF.  
 2. Rises Time = 10ns, max.  
 Source Impedance = 50 ohms.



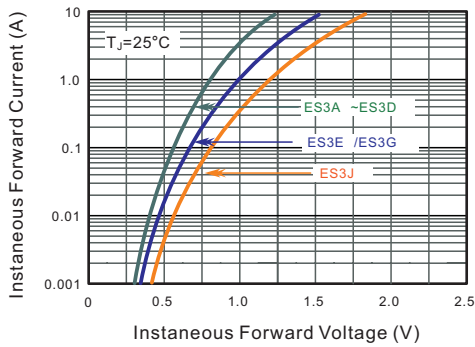
**Fig.2 Maximum Average Forward Current Rating**



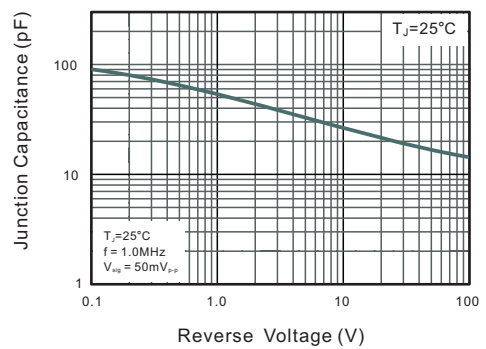
**Fig.3 Typical Reverse Characteristics**



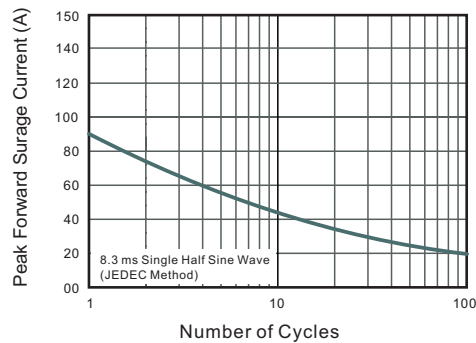
**Fig.4 Typical Forward Characteristics**



**Fig.5 Typical Junction Capacitance**



**Fig.6 Maximum Non-Repetitive Peak Forward Surge Current**

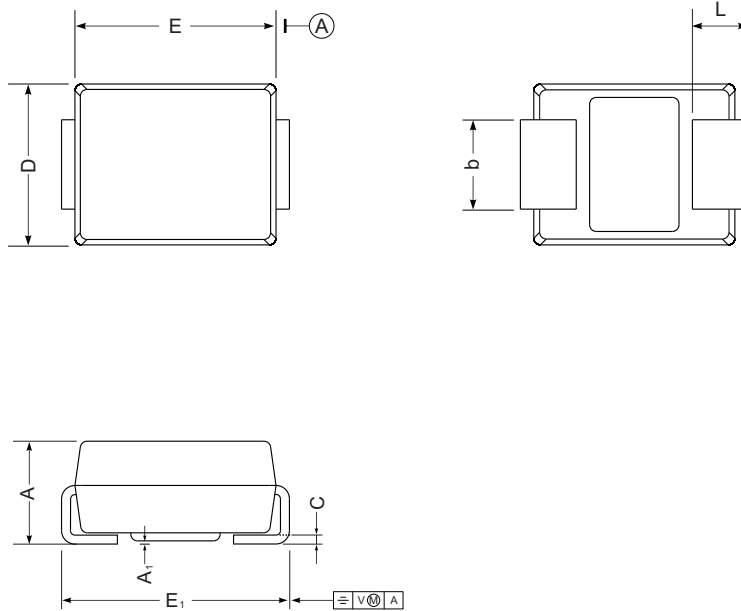


# ES3A THRU ES3J

## PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

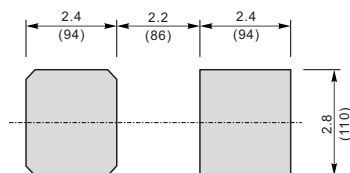
SMB



SMB mechanical data

UNIT		A	E	D	E <sub>1</sub>	A <sub>1</sub>	L	C	b
mm	max	2.44	4.70	3.94	5.59	0.20	1.5	0.305	2.2
	min	2.13	4.06	3.3	5.08	0.05	0.8	0.152	1.9
mil	max	96	185	155	220	7.9	59	12	87
	min	84	160	130	200	2.0	32	6	75

### The recommended mounting pad size



Unit :  $\frac{\text{mm}}{\text{mil}}$